













LAIRD CONNECTIVITY Wi-Fi + BLUETOOTH MODULES WITH NXP SILICON



Part Number	453-00075-K1	453-00081-K1, 453-00082-K1	DVK-ST60-SIPT	DVK-ST60-2230C	453-00072-K1	455-00039
Type Name	 Sterling 70 Series SIP	 Sterling 70 Series M.2	 Sterling 60 Series SIP	 Sterling 60 Series M.2	 Summit SOM 8M Plus	 60 Series SOM
NXP Chipset	88W9098	88W9098	88W8997	88W8997	i.MX 8M Plus 88W8997	88W8997
Wi-Fi®	 2x2 CDW DB (2.4/5 GHz)	 2x2 CDW DB (2.4/5 GHz)	 2x2 DB (2.4/5 GHz)	 2x2 DB (2.4/5 GHz)	 2x2 DB (2.4/5 GHz)	 2x2 DB (2.4/5 GHz)
Bluetooth®	5.3 BR/EDR/LE	5.3 BR/EDR/LE	5.3 BR/EDR/LE	5.3 BR/EDR/LE	5.3 BR/EDR/LE	5.3 BR/EDR/LE
Wi-Fi Host Interface	SDIO, PCIe	SDIO, PCIe	SDIO, PCIe, USB	SDIO, PCIe, USB	Various	Various
Bluetooth Interface	UART	UART	UART, SDIO, USB	UART, SDIO, USB	Various	Various
Dimensions (mm)	18 x 20 x 2.8	22 x 30 x 3.1	13 x 14 x 1.87	22 x 30 x 3.3	40 x 47 x 4.6	30 x 30 x 2.8
Certifications	FCC, ISED, EU, MIC, AS-NZS	FCC, ISED, EU, MIC, AS-NZS	FCC, ISED, EU, MIC, AS-NZS	FCC, ISED, EU, MIC, AS-NZS	FCC, ISED, EU, MIC, AS-NZS	FCC, ISED, EU, MIC, AS-NZS
Operating Temperature	-40 °C to +85 °C	-40 °C to +85 °C	-30 °C to +85 °C	-30 °C to +85 °C	-30 °C to +85 °C	-30 °C to +85 °C
Software Support	Linux® OS	Linux® OS	Linux® OS, Android™ OS	Linux® OS, Android™ OS	Linux® OS, RTOS	Linux® OS